



Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)} max	I _{D MAX} T _A = +25°C
		25mΩ @ V _{GS} = 4.5V	6.9A
N-Channel	12V	30mΩ @ V _{GS} = 2.5V	6.3A
		38mΩ @ V _{GS} = 1.8V	5.5A

Description

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load Switch
- Power Management Functions
- Portable Power Adaptors

Features

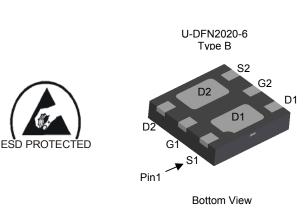
- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Max Height
- ESD protected gate.
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

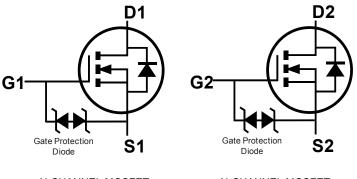
DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: U-DFN2020-6 Type B
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 @
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (approximate)





N-CHANNEL MOSFET

ET N-CHANNEL MOSFET Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN1025UFDB-7	U-DFN2020-6 Type B	3000/Tape & Reel
DMN1025UFDB-13	U-DFN2020-6 Type B	10000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/quality/product_compliance_definitions/.

Marking Information

	NB	ΥM	
•			

NB = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	201	2	2013		2014	20	15	2016		2017	2	2018
Code	Z		А		В	()	D		E		F
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		•	-	-	-	<u>^</u>	-	<u>^</u>	<u>^</u>	-		6



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V _{DSS}	12	V	
Gate-Source Voltage		V _{GSS}	±10	V	
Continuous Drain Current (Note 5))/ - 45)/	Steady State	T _A = +25°C T _A = +70°C	ID	6.9 5.5	A
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t < 5s	T _A = +25°C T _A = +70°C	ID	8.8 7.0	A
Maximum Continuous Body Diode Forward Curre	ent (Note 5)	Is	1	A	
Pulsed Drain Current (10µs pulse, duty cycle = 1	%)	I _{DM}	35	А	
Avalanche Current (Note 6) L = 0.1mH		I _{AS}	9.8	А	
Avalanche Energy (Note 6) L = 0.1mH			E _{AS}	4.8	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Units		
Total Dower Dissipation (Note E)	Steady State	D	1.7	W	
Total Power Dissipation (Note 5)	t < 5s	PD	2.9		
Thermal Deviatorse, Junction to Ambient (Nato 5)	Steady State		71		
Thermal Resistance, Junction to Ambient (Note 5)	t < 5s	R _{θJA}	43	°C/W	
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	13			
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to 150	°C	

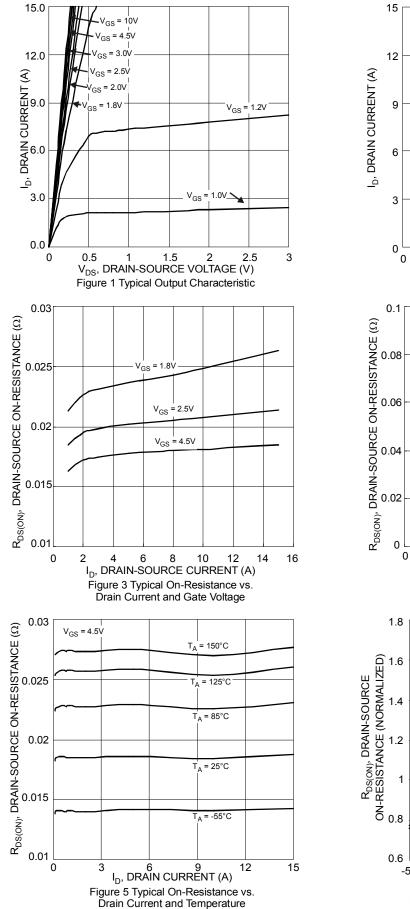
Electrical Characteristics N-CHANNEL (@T_A = +25°C, unless otherwise specified.)

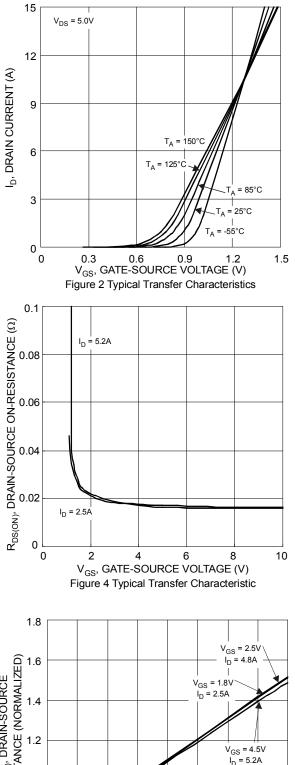
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)				•		-	
Drain-Source Breakdown Voltage	BV _{DSS}	12	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	_	1.0	μA	V_{DS} = 12V, V_{GS} = 0V	
Gate-Source Leakage	I _{GSS}	—	—	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(th)}	0.4	—	1	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
		—	18	25		V _{GS} = 4.5V, I _D = 5.2A	
Static Drain-Source On-Resistance	R _{DS} (ON)	_	20	30	mΩ	V _{GS} = 2.5V, I _D = 4.8A	
	. ,	_	25	38		V _{GS} = 1.8V, I _D = 2.5A	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	V _{GS} = 0V, I _S = 5.4A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	917	_	pF		
Output Capacitance	Coss	_	120	_	pF	V _{DS} = 6V, V _{GS} = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	102	_	pF		
Gate Resistance	Rg	_	11.4		Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz	
Total Gate Charge (V _{GS} = 4.5V)		_	12.6	_	nC		
Total Gate Charge (V _{GS} = 8V)	Qg	_	23.1		nC		
Gate-Source Charge	Q _{gs}	_	1.3	_	nC	V _{DS} = 10V, I _D = 6.8A	
Gate-Drain Charge	Q _{gd}	_	1.6	_	nC	7	
Turn-On Delay Time	t _{D(on)}	_	3.0	_	ns		
Turn-On Rise Time	tr	_	9.3		ns	$V_{DD} = 6V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(off)}	_	17.2	_	ns	$R_{L} = 1.1\Omega, R_{G} = 1\Omega$	
Turn-Off Fall Time	t _f	_	2.8	_	ns	7	
Body Diode Reverse Recovery Time	trr	_	6.8		nS	I _S = 5.4A, dI/dt = 100A/µs	
Body Diode Reverse Recovery Charge	Qrr	_	1.1	_	nC	I _S = 5.4A, dl/dt = 100A/µs	

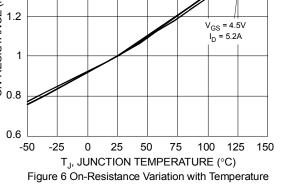
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. 6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing. Notes:



DMN1025UFDB

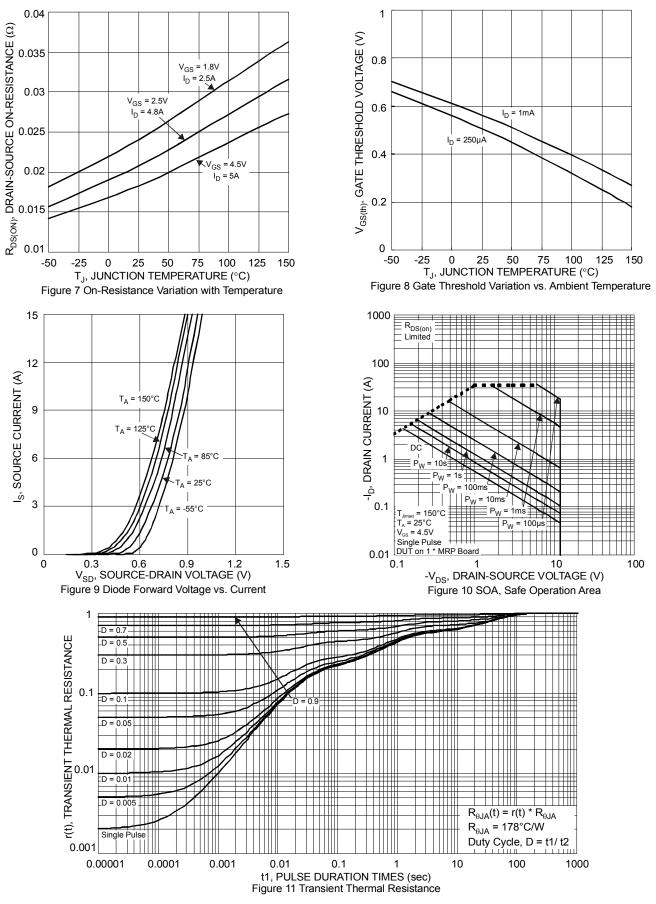








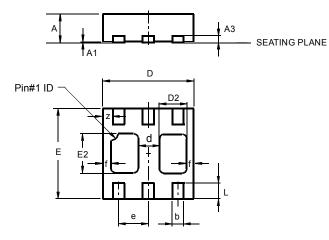
DMN1025UFDB





Package Outline Dimensions

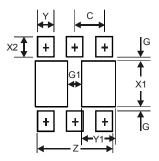
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



U-DFN2020-6								
Туре В								
Dim	Min	Max	Тур					
Α	0.545	0.605	0.575					
A1	0	0.05	0.02					
A3	-	_	0.13					
b	0.20	0.30	0.25					
D	1.95	2.075	2.00					
d	_		0.45					
D2	0.50	0.70	0.60					
e		_	0.65					
Е	1.95	2.075	2.00					
E2	0.90	1.10	1.00					
f	_		0.15					
L	0.25	0.35	0.30					
z	_	_	0.225					
All	Dimens	ions in	mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
С	0.65



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